

DS-7408



Application

6~ 10 Layer PCB

Surface Mounted Technology

UV Shield & AOI



DS-7408

Higher Glass Transition Temperature(Tg)

Superior Chemical Resistance

Lower Water Absorption

High Dimensional Stability

Lower Thermal Expansion

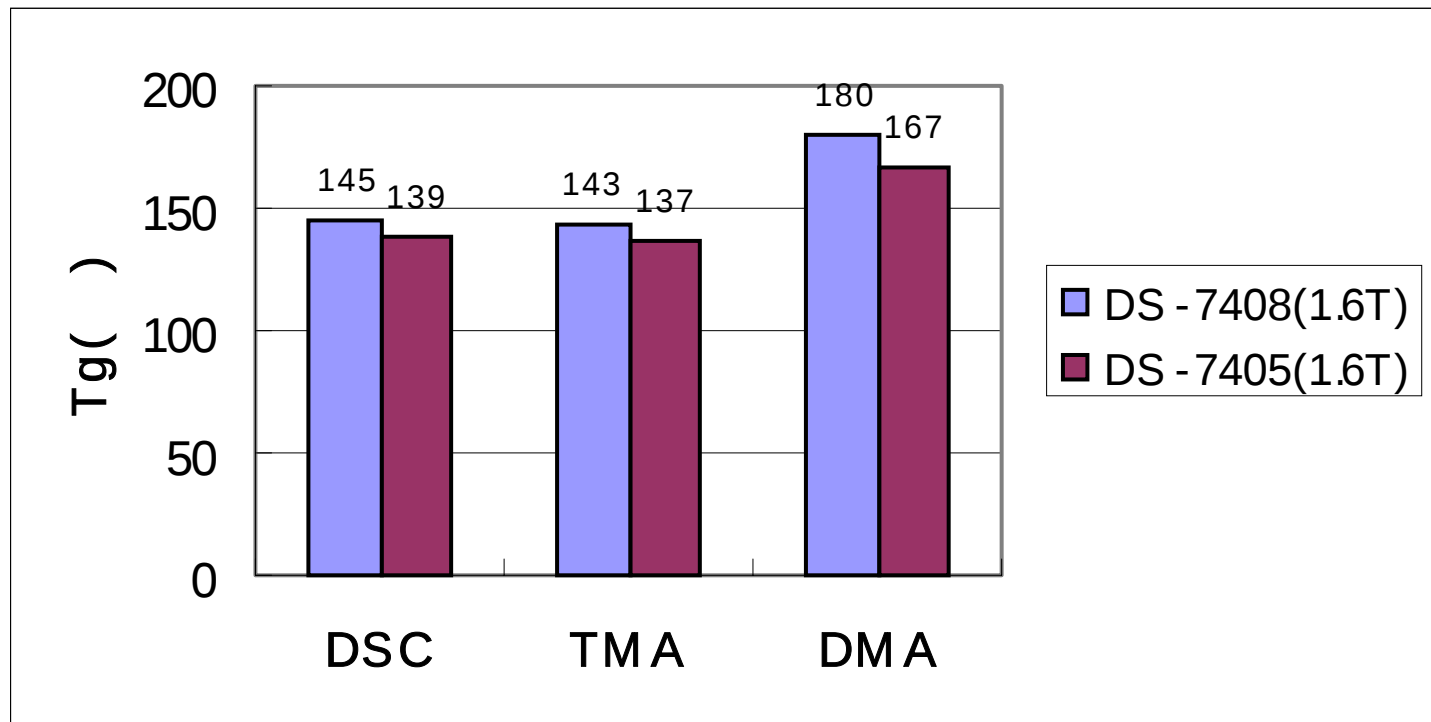


DS-7408 Bonding Sheet

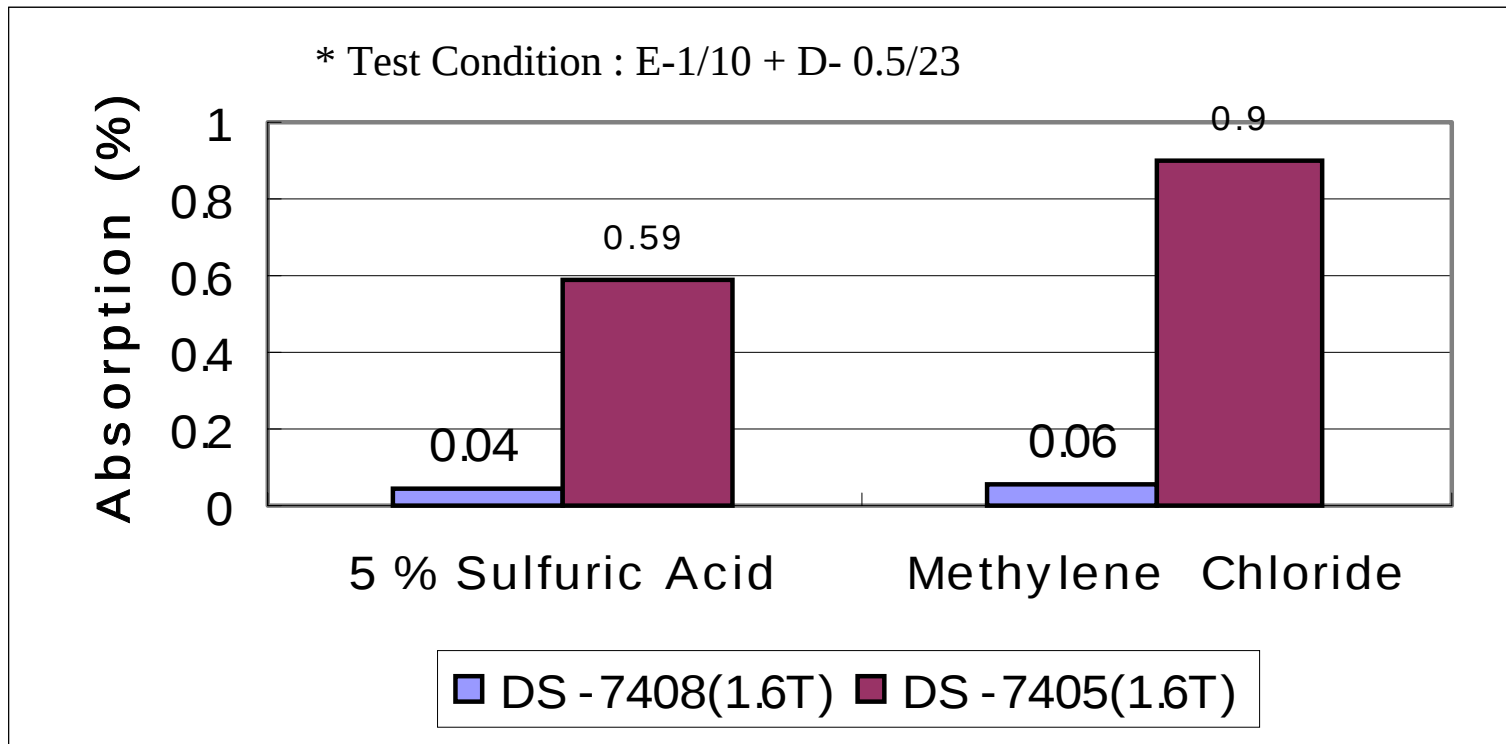
- Tetrafunctional System
- DS-7405

Grade	G/F	R/C	R/F	G/T
DS-7408 BS-2	7628	42	18 ~ 20	85 ± 10
DS-7408 BS-4	2116	53	18 ~ 20	85 ± 11
DS-7408 BS-7	1080	64	18 ~ 20	85 ± 12

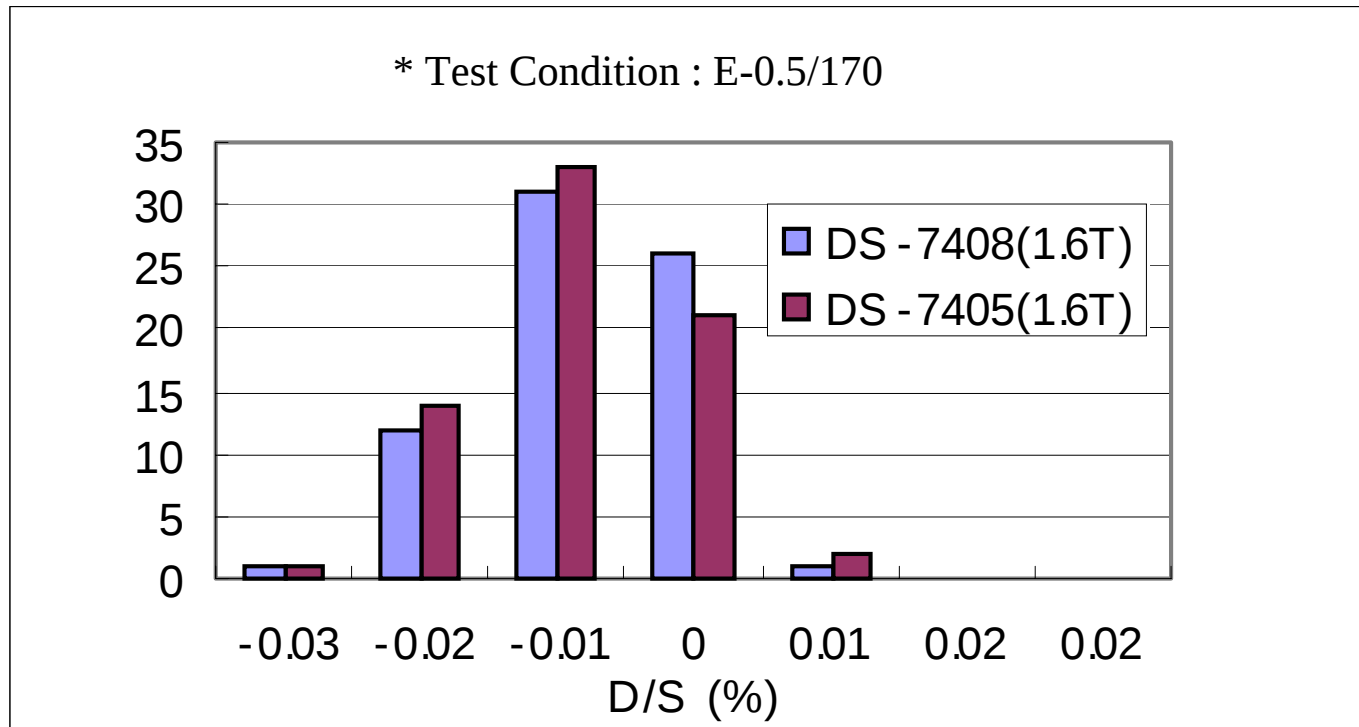
Glass Transition Temp.(Tg)



Chemical Resistance



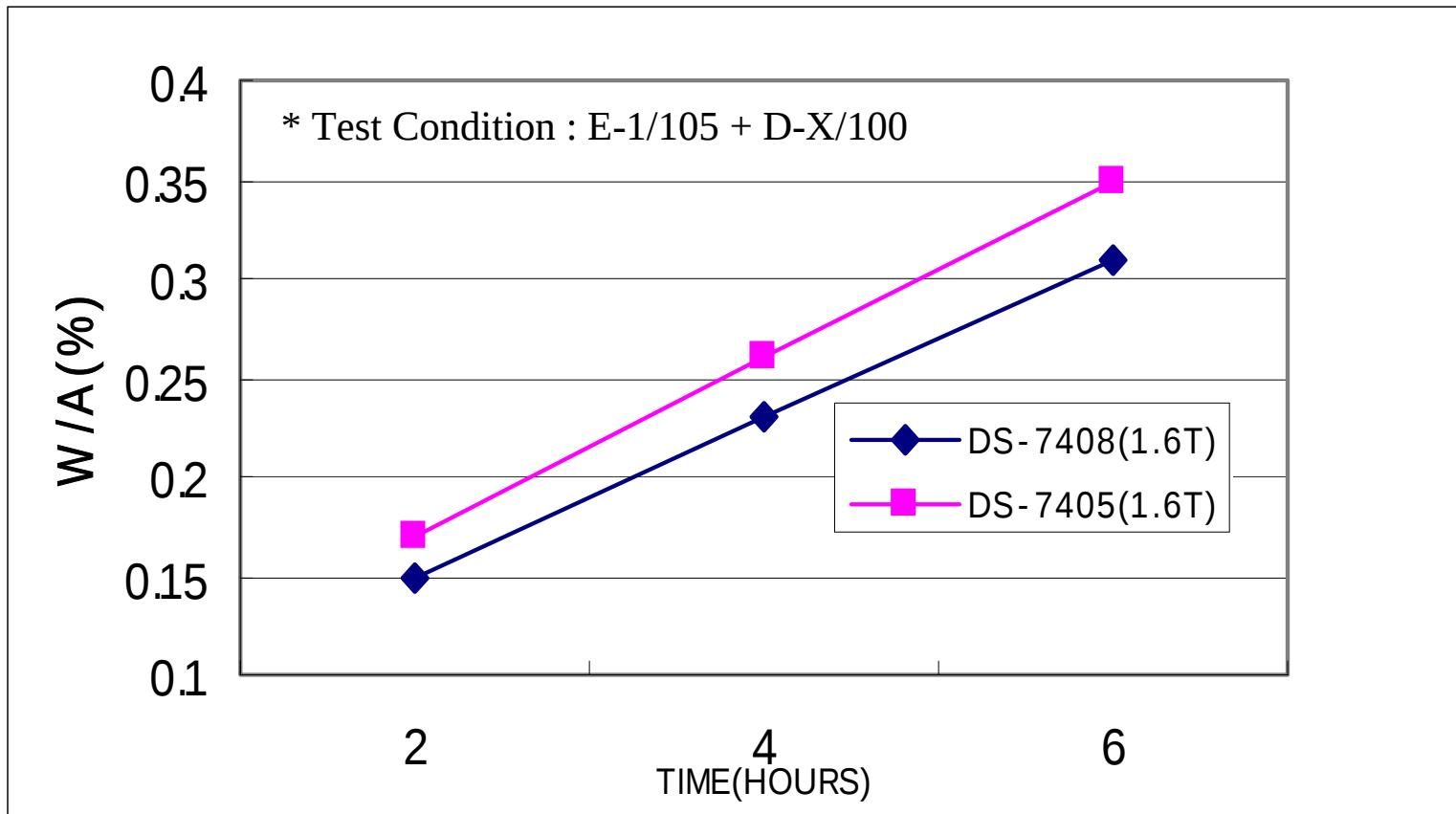
Dimensional Stability



Solder Resistance

		MLB(1.6T)		RIGID(1.6T)	
		DS - 7408	DS - 7405	DS - 7408	DS - 7405
PCT	121 /100% RH/1.5 HR + @288 Solder Dip	Over 180 secs	Blister	Over 180 secs	Over 180 secs
	121 /100% RH/3.0 HR +@288 Solder Dip	Blister	-	Over 180 secs	Blister
Boiling Water	D-2/100 + 288 Solder Dip	Over 180 secs	Over 180 secs	-	-
	D-4/100 + 288 Solder Dip	Over 180 secs	Blister	-	-
	D-6/100 + 288 Solder Dip	Over 180 secs	-	-	-

Water Absorption



Properties

		DS - 7408(1.6t)	DS - 7405(1.6t)
Tg	DSC	145	139
	TMA	143	137
	DMA	180	167
	TGA	329	327
CTE(ppm)	$\alpha 1$	42	58
	$\alpha 2$	251	293
Z	%, @250	3.1	3.8
D/S	%, E -0.5/ 170	-0.03 ~ 0.01	-0.03 ~ 0.01
Target	%/ 489 mm, After Pressing	- 0.011 ~ -0.007	-0.011 ~ -0.007

		DS - 7408(1.6t)	DS - 7405(1.6t)
	E - 1/105 + D - 2/100	0.15	0.17
	E - 1/105 + D - 6/100	0.31	0.35
	E - 1/105 + D - 24/100	0.08	0.1
	%, CH C , D-0.5/23	0.59	0.9
	%, 5% H SO , D-0.5/23	0.04	0.06
	D - 2/100	1.70E +13	1.80E + 13
	D - 6/100	1.30E + 13	1.45E + 13
P.C.T. (MassLAM)	121 /100% RH/1.0 HR + @288	No Blister	No Blister
	121 /100% RH/1.0 HR + @288	No Blister	Blister
	@ 260	over 180 secs	over 180 secs
(MassLAM)	D - 4/100 + @288	No Blister	Blister
Peel Strength	, 35μm, kg/cm	1.7	1.86
	MASS LAM , 35μm.kg/cm	0.36	1.69
	UL 94	V - 0	V - 0
UV	-	가	OPTION
	-	YELLOW	NATURAL

Press Cycle

